

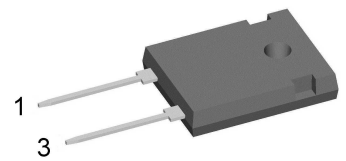
HiPerFRED

$$\begin{aligned} V_{RRM} &= 600 \text{ V} \\ I_{FAV} &= 30 \text{ A} \\ t_{rr} &= 25 \text{ ns} \end{aligned}$$

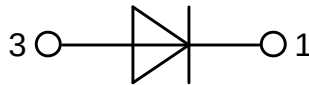
High Performance Fast Recovery Diode
Low Loss and Soft Recovery
Single Diode

Part number

DSEP30-06B



Backside: cathode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low I_{rm} -values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low I_{rm} reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-247

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms .Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

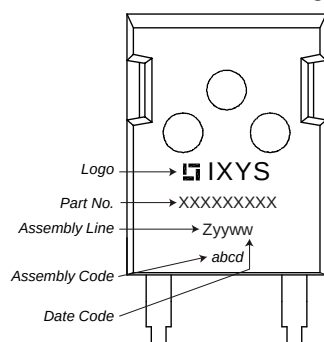
Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

Fast Diode				Ratings				
Symbol	Definition	Conditions		min.	typ.	max.	Unit	
V _{RSM}	max. non-repetitive reverse blocking voltage	T _{VJ} = 25°C				600	V	
V _{RRM}	max. repetitive reverse blocking voltage	T _{VJ} = 25°C				600	V	
I _R	reverse current, drain current	V _R = 600 V	T _{VJ} = 25°C			250	μA	
		V _R = 600 V	T _{VJ} = 150°C			2	mA	
V _F	forward voltage drop	I _F = 30 A	T _{VJ} = 25°C			2.51	V	
		I _F = 60 A				3.19	V	
		I _F = 30 A	T _{VJ} = 150°C			1.61	V	
		I _F = 60 A				2.24	V	
I _{FAV}	average forward current	T _C = 120°C rectangular d = 0.5	T _{VJ} = 175°C			30	A	
V _{F0}	threshold voltage	} for power loss calculation only				0.84	V	
r _F	slope resistance					19.6	mΩ	
R _{thJC}	thermal resistance junction to case					0.9	K/W	
R _{thCH}	thermal resistance case to heatsink				0.25		K/W	
P _{tot}	total power dissipation	T _C = 25°C				165	W	
I _{FSM}	max. forward surge current	t = 10 ms; (50 Hz), sine; V _R = 0 V		T _{VJ} = 45°C		250	A	
C _J	junction capacitance	V _R = 400 V f = 1 MHz		T _{VJ} = 25°C	26		pF	
I _{RM}	max. reverse recovery current	} I _F = 30 A; V _R = 300 V -di _F /dt = 200 A/μs		T _{VJ} = 25 °C	2.5		A	
				T _{VJ} = 100 °C	4.5		A	
t _{rr}	reverse recovery time			T _{VJ} = 25 °C	25		ns	
				T _{VJ} = 100 °C	70		ns	

Package TO-247			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			70	A
T_{VJ}	virtual junction temperature		-55		175	°C
T_{op}	operation temperature		-55		150	°C
T_{stg}	storage temperature		-55		150	°C
Weight				6		g
M_D	mounting torque		0.8		1.2	Nm
F_C	mounting force with clip		20		120	N

Product Marking

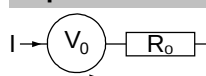


Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP30-06B	DSEP30-06B	Tube	30	475408

Similar Part	Package	Voltage class
DSEP29-06A	TO-220AC (2)	600
DSEP29-06AS	TO-263AB (D2Pak) (2)	600
DSEP30-06A	TO-247AD (2)	600
DSEP30-06BR	ISOPLUS247 (2)	600
DHG30I600HA	TO-247AD (2)	600
DHG30I600PA	TO-220AC (2)	600
DHG30IM600PC	TO-263AB (D2Pak) (2)	600

Equivalent Circuits for Simulation

* on die level

 $T_{VJ} = 175\text{ °C}$ 

Fast Diode

 $V_{0\text{ max}}$ threshold voltage

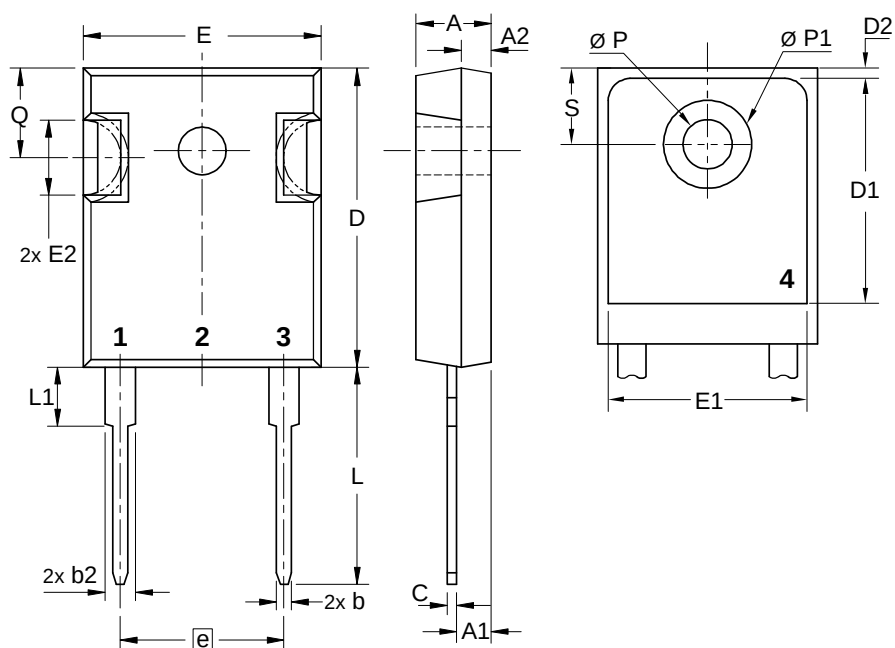
0.84

V

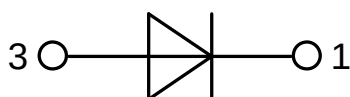
 $R_{0\text{ max}}$ slope resistance *

2.4

mΩ

Outlines TO-247


Sym.	Inches		Millimeter	
	min.	max.	min.	max.
A	0.185	0.209	4.70	5.30
A1	0.087	0.102	2.21	2.59
A2	0.059	0.098	1.50	2.49
D	0.819	0.845	20.79	21.45
E	0.610	0.640	15.48	16.24
E2	0.170	0.216	4.31	5.48
e	0.430	BSC	10.92	BSC
L	0.780	0.800	19.80	20.30
L1	-	0.177	-	4.49
Ø P	0.140	0.144	3.55	3.65
Q	0.212	0.244	5.38	6.19
S	0.242	BSC	6.14	BSC
b	0.039	0.055	0.99	1.40
b2	0.065	0.094	1.65	2.39
b4	0.102	0.135	2.59	3.43
c	0.015	0.035	0.38	0.89
D1	0.515	-	13.07	-
D2	0.020	0.053	0.51	1.35
E1	0.530	-	13.45	-
Ø P1	-	0.29	-	7.39



Fast Diode

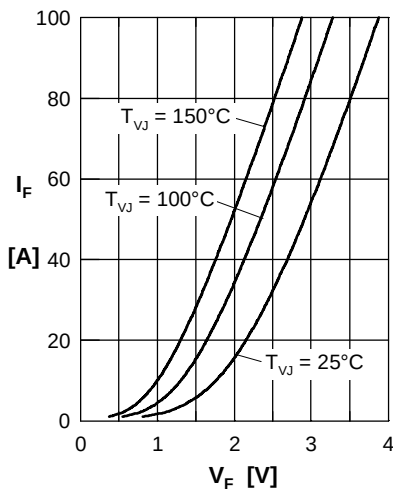


Fig. 1 Forward current I_F versus V_F

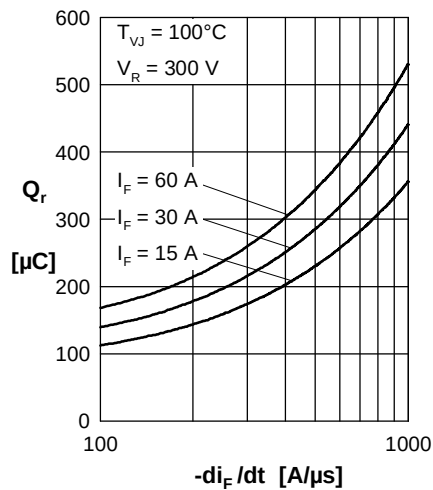


Fig. 2 Typ. reverse recov. charge Q_r versus $-di_F/dt$

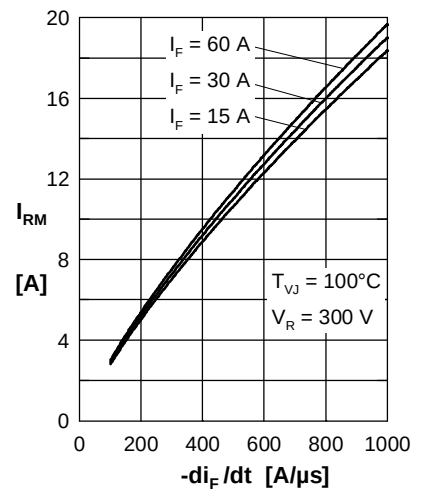


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

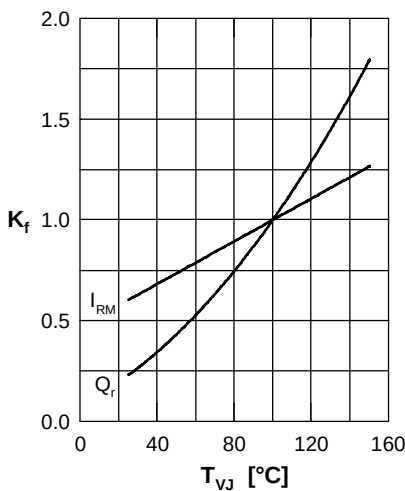


Fig. 4 Dynamic parameters Q_r , I_{RM} versus T_{VJ}

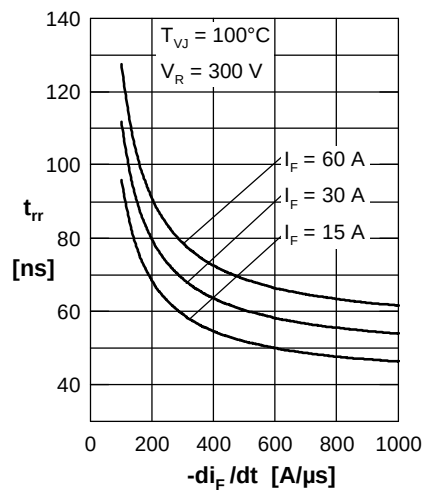


Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

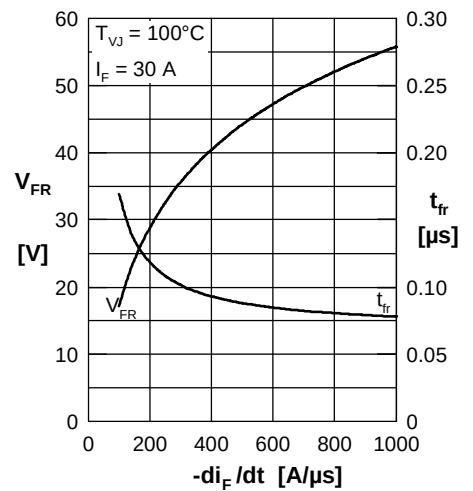


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

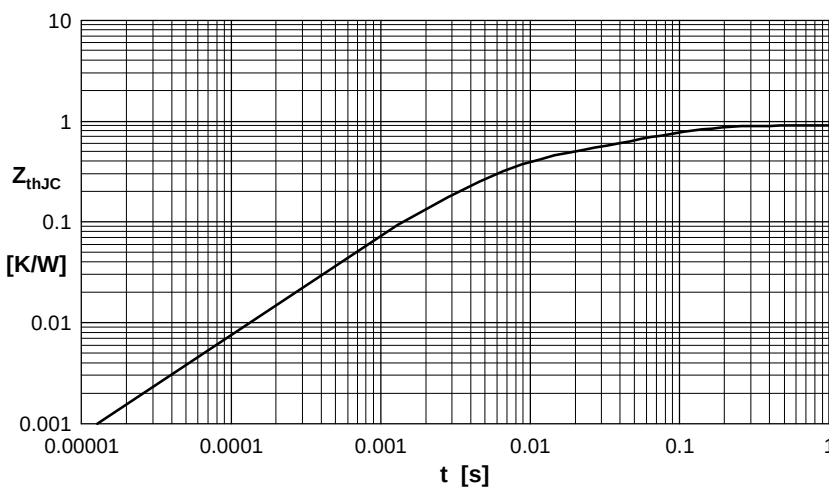


Fig. 7 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.030	0.001
2	0.080	0.030
3	0.300	0.006
4	0.490	0.060